

## Design Example Report

<b>Title</b>	<i>High Efficiency 40 W Standby Power Supply Using TOPSwitch™-JX TOP267KG</i>
<b>Specification</b>	110 VDC – 400 VDC Input; 12 V, 3.33 A, Output
<b>Application</b>	PC Standby Supply
<b>Author</b>	Applications Engineering Department
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### Summary and Features

- Highly energy efficient
  - Full load efficiency >89%
  - Efficiency >87% above 10% load
  - Average efficiency >89% (25%, 50%, 75%, 100% and 20%, 50%, 100% load points)
  - Simplifies meeting ENERGY STAR 2.0, 80 Plus and EuP requirements
- Low cost, low component count and small PCB footprint solution
  - Performance met without synchronous output rectification
  - 132 kHz operation optimized core size and efficiency performance
  - Surface mount low-profile eSOP™ package
- Integrated protection and reliability features
  - Line undervoltage lock out (UVLO)
  - Primary sensed output overvoltage shutdown (OVP). Latched OVP condition can be reset with a fast AC reset circuit.
  - Auto recovery output over current (OCP)
  - Meets limited power source (LPS) <100 VA requirement with a single point of failure
  - Accurate thermal shutdown with large hysteresis

### PATENT INFORMATION

The products and applications illustrated herein (including transformer construction and circuits external to the products) may be covered by one or more U.S. and foreign patents, or potentially by pending U.S. and foreign patent applications assigned to Power Integrations. A complete list of Power Integrations' patents may be found at [www.powerint.com](http://www.powerint.com). Power Integrations grants its customers a license under certain patent rights as set forth at <http://www.powerint.com/ip.htm>.

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**Important Note:**

Although this board is designed to satisfy safety isolation requirements, the engineering prototype has not been agency approved. Therefore, all testing should be performed using an isolated power source to provide the DC input to the prototype board.



## 1 Introduction

This document is an engineering report describing standby power supply utilizing a TOPSwitch-JX TOP267KG. This power supply is intended as a general purpose evaluation platform that operates from 110 VDC to 400 VDC input and provides a 12 V, continuous 40 W output.

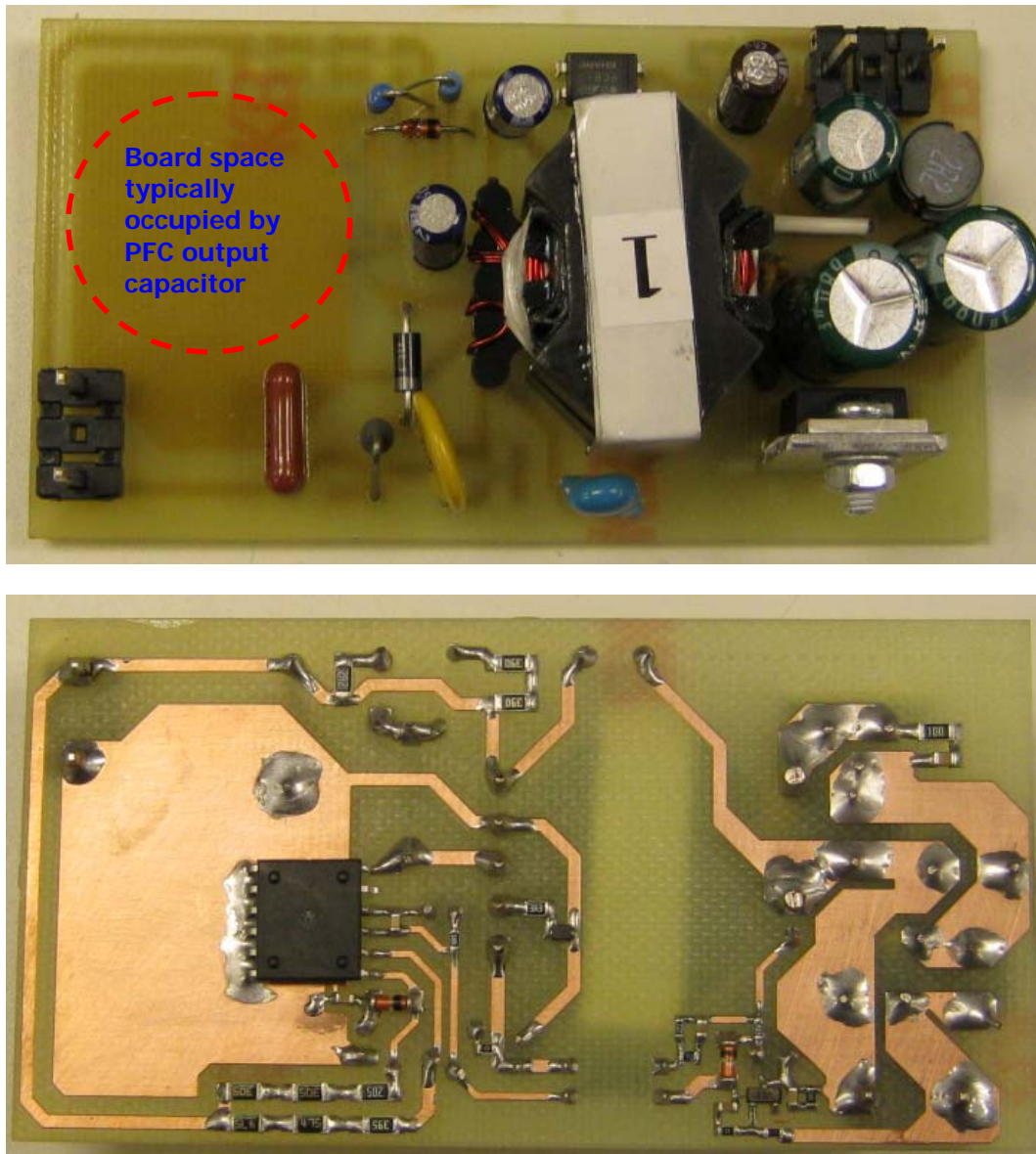


Figure 1 – Populated Circuit Board Photographs.

**Note:** This design eliminates need for external heat sink for the integrated power supply controller IC by making use of board space underneath the PFC output capacitor.

This standby supply was designed to meet 80 Plus Standard and Energy Star 2.0 >87% average-efficiency.

This power supply offers these various protection features using a low component count circuit:

- Overvoltage protection (OVP) with optional fast AC reset
- Primary-side sensed output overload protection, even with a single fault
- Open-loop protection
- Auto-restart overload protection
- Accurate thermal overload protection with auto-recovery using a large hysteresis

The document contains the power supply specification, schematic, bill of materials, transformer documentation, printed circuit layout, and performance data.



## 2 Power Supply Specification

The table below represents the minimum acceptable performance of the design. Actual performance is listed in the results section.

Description	Symbol	Min	Typ	Max	Units	Comment
<b>Input</b> Voltage No-load Input Power	$V_{IN}$	110		400 0.135	VDC W	
<b>Output</b> Output Voltage Output Ripple Voltage Output Current <b>Total Output Power</b> Continuous Output Power	$V_{OUT}$ $V_{RIPPLE}$ $I_{OUT}$ $P_{OUT}$		12		V mV A W	$\pm 5\%$ 20 MHz bandwidth
<b>Efficiency</b> Full Load Required average efficiency at 25, 50, 75 and 100 % of $P_{OUT}$	$\eta$ $\eta_{ES2.0}$	89 83			% %	Measured at $P_{OUT}$ 25 °C Per ENERGY STAR V2.0
<b>Protection</b> Over Power Overvoltage				60 26	W VDC	Auto-recovery Latching
<b>Environmental</b> Safety						Designed to meet IEC950 / UL1950 Class II
Ambient Temperature	$T_{AMB}$	0	25	40	°C	Free convection, sea level





## 4 Circuit Description

This flyback converter configuration, built around the TOP267KG (U1), provides a 12 V output, and delivers a load current of 3.33 A. This power supply operates over an input range of 110 VDC to 400 VDC. The output is secondary-side regulated using voltage reference U3.

### 4.1 TOPSwitch-JX Primary

Resistors R4, R5 and R6 provide a current into the VOLTAGE MONITOR (V) pin of U1 proportional to the DC voltage across high-voltage bypass capacitor C1. Resistor R10 provides an offset current into the V pin to reduce the current drawn from the DC bus via R4, R5 and R6. This reduces the dissipation in R4, R5 and R6 which significantly reduces no-load and light load input power. The values shown set the undervoltage threshold to 80 VDC, the point at which current into the V pin exceeds 25  $\mu$ A. At this point switching is enabled and the power supply starts up.

An RCDZ clamp network (D1, R7, R8, R9, C2 and VR1) limits the drain voltage of U1 to below 725 V after the MOSFET inside U1 turns OFF. This configuration was selected as it maximizes efficiency across the load range.

Diode D3 rectifies the bias winding output of transformer T1. Resistor R13 and capacitor C6 filter the output of the bias winding. This provides the necessary bias supply for the optocoupler U2B. The voltage across capacitor C6 was adjusted via the number of bias winding turns to be  $\sim$ 9 V at no-load and 400 VDC input. This voltage value minimizes no-load consumption but ensures that sufficient voltage is present on the optocoupler collector to maintain regulation.

The secondary-side feedback circuitry maintains output voltage regulation via U2A. A change in current through the optocoupler diode causes a change in the current out of the optocoupler transistor (which is proportional to the CTR of the optocoupler) and into CONTROL (C) pin of IC U1. Current into the C pin changes the duty cycle of the internal MOSFET thereby regulating the output voltage.

Zener diode VR2 provides output overvoltage protection. Any fault condition which causes the power supply output to exceed regulation limits also causes the voltage across the bias winding to increase. Consequently, Zener diode VR2 breaks down and sufficient current flows into the V pin of U1 via D2 to initiate OVP. A resistor can be added in series with VR2 that limits the current into the V pin and changes the latching to self-recovering shutdown.

Resistors R1, R2, R3 and R11 provide output power limiting. By reducing the current limit as a function of the input voltage a relatively constant overload power is achieved.



#### **4.2 Output Rectification**

Diode D4 provides rectification for the 12 V output, and low-ESR capacitors C9 and C15 provides filtering. To eliminate high frequency switching noise, a post filter was added (L1 and C10).

The snubber network comprised of R14 and C8 damp oscillations on D4 caused by the transformer winding leakage inductance, reducing radiated EMI and diode voltage stress.

#### **4.3 Output Feedback**

The output voltage is controlled using shunt regulator U3. Resistors R19 and R20 sense the output voltage, forming a resistor divider connected to the reference input of IC U3. Changes in the output voltage and hence the voltage at the reference input of U3 results in changes in the cathode voltage of IC U3 and therefore optocoupler LED current. This changes the current into the C pin of U1 and acts to maintain output regulation.

Capacitor C13 introduces a pole at DC, rolling off the gain of U3. Resistor R17 and capacitor C11 provides the additional phase boost to achieve stable power supply operation. Capacitor C14 was added after it was found that switching noise was being injected into the reference pin of IC U3.

Resistor R16 sets the overall loop gain and limits current through U3A during transient conditions.

To reduce power dissipation in the feedback circuit (and lower no-load consumption) a D rank optocoupler was selected with the value of resistor R16 increased to offset the increase in loop gain. A low minimum cathode current (130  $\mu$ A) reference was selected for U3 to also reduce dissipation.

#### **4.4 Fast AC Reset**

The TOPSwitch-JX family has a fast AC reset function which can be configured on the EXTERNAL CURRENT LIMIT (X) pin (as shown in Figure 3). Should the device stop switching due to a latching OVP fault condition, the circuit connected to the X pin will force  $I_X$  to exceed  $I_{X(TH)} = -27 \mu$ A (typical) and reset the latch when the AC input is disconnected or falls below a set threshold value.

In Figure 3, R1, R2 and C1 set the time after AC is removed before the latch is reset. A higher gain BJT  $Q_R$  is desirable to allow a higher resistance value for R1 and lower capacitance value for C1, and thus minimize the circuit dissipation.

Consult Application Note AN-47 TOPSwitch-JX Family Design Guide for further information.

#### **4.5 Reduction of No-Load Input Power**

Configuring the optocoupler as one of the transistors in a Darlington pair (as shown in Figure 4) typically reduces the no-load power consumption below 100 mW.

The increased gain of the Darlington reduces the optocoupler LED (feedback) current required to provide a given CONTROL pin current to maintain output regulation. As the secondary feedback current is sourced from the output, it represents an output load and therefore lowering the feedback current reduces this load and hence input power consumption. As the reduction is a function of the output voltage this approach is most effective for designs where the output feedback is derived from higher output voltage (>12 V).

The following additional changes should be made to Figure 2 in order to ensure system stability if the changes recommended in figure 4 for reduction of no-load input power are to be used.

1. The gain of the optocoupler should be limited to a CTR rank of A (80-160%).
2. A 6.8 k $\Omega$  resistor should be added across optocoupler diode U2A.
3. Resistor R16 needs to be increased in order to compensate for increased gain.
4. If this arrangement is used, components R16, R17, C11 and C13 need to be changed to adjust loop response.

Consult Power Integrations Application Note AN-47 "TOPSwitch-JX Family Design Guide" for further information.

### 5 PCB Layout

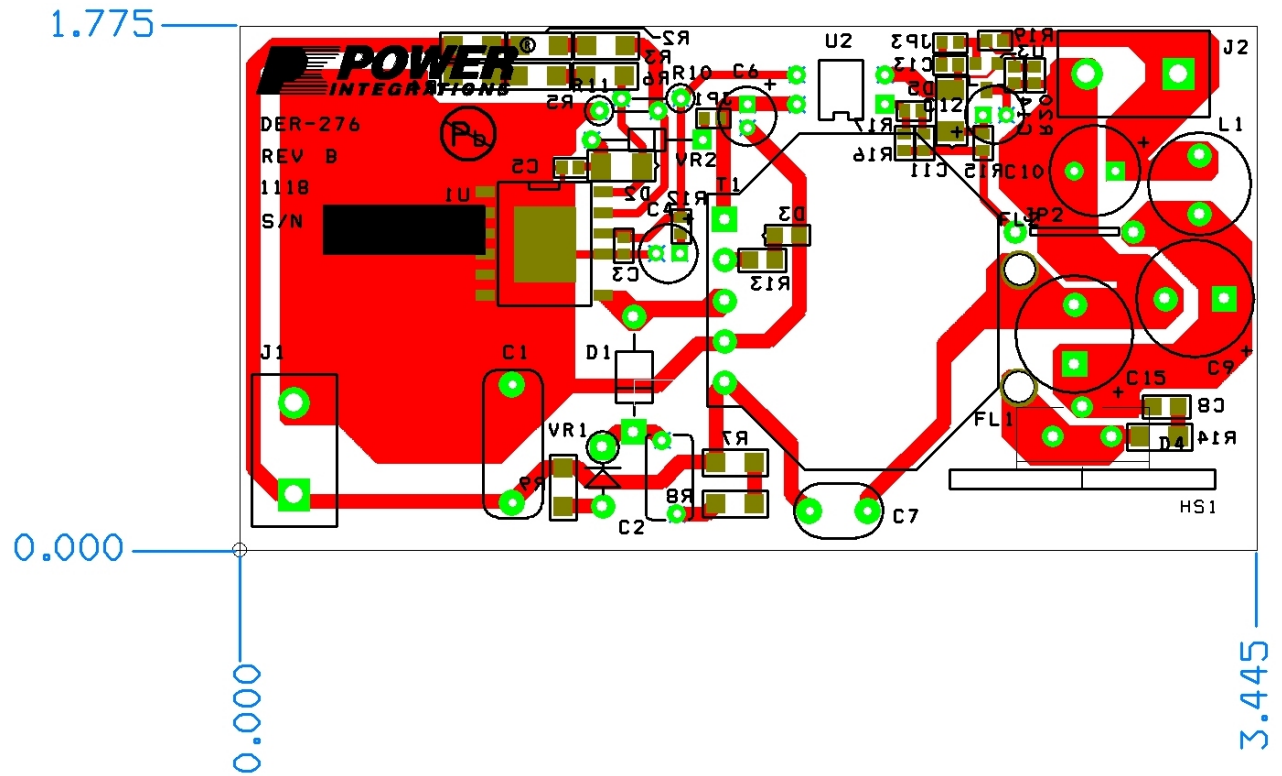


Figure 5 – Printed Circuit Layout (1.775" x 3.445").



## 6 Bill of Materials

Item	Qty	Ref Des	Description	Mfg Part Number	Manufacturer
1	1	C1	10 nF, 630 V, Film	ECQ-E6103KF	Panasonic
2	1	C2	2200 pF, 1 kV, Disc Ceramic	562R5GAD22	Vishay
3	3	C3 C5 C13	100 nF 25 V, Ceramic, X7R, 0603	ECJ-1VB1E104K	Panasonic
4	1	C4	47 $\mu$ F, 25 V, Electrolytic, Gen. Purpose, (5 x 11)	ECA-1EM470	Panasonic
5	1	C6	22 $\mu$ F, 50 V, Electrolytic, Low ESR, 900 m $\Omega$ , (5 x 11.5)	ELXZ500ELL220MEB5D	Nippon Chemi-Con
6	1	C7	2.2 nF, 250 VAC, Film, X1Y1	DE2E3KY222MA2BM01	Murata
7	1	C8	1 nF, 100 V, Ceramic, X7R, 0805	ECJ-2VB2A102K	Panasonic
8	2	C9 C15	680 $\mu$ F, 25 V, Electrolytic, Very Low ESR, 23 m $\Omega$ , (10 x 20)	EKZE250ELL681MJ20S	Nippon Chemi-Con
9	1	C10	220 $\mu$ F, 25 V, Electrolytic, Very Low ESR, 72 m $\Omega$ , (8 x 11.5)	EKZE250ELL221MHB5D	Nippon Chemi-Con
10	1	C11	47 nF 16 V, Ceramic, X7R, 0603	ECJ-1VB1C473K	Panasonic
11	1	C12	2.2 $\mu$ F, 50 V, Electrolytic, Gen. Purpose, (5 x 11)	EKME500ELL2R2ME11D	Nippon Chemi-Con
12	1	C14	3.3 nF 50 V, Ceramic, X7R, 0603	GRM188R71H332KA01D	Murata
13	1	D1	800 V, 1 A, Fast Recovery Diode, 500 ns, DO-41	FR106	Diodes Inc.
14	2	D2 D5	75 V, 0.15 A, Fast Switching, 4 ns, MELF	LL4148-13	Diodes Inc.
15	1	D3	100 V, 0.2 A, Fast Switching, 50 ns, SOD-323	BAV19WS-7-F	Diodes Inc.
16	1	D4	100 V, 30 A, Schottky, TO-220AB	NTST30100SG	ON Semi
17	2	FL1 FL2	PCB Terminal Hole, #22 AWG	N/A	N/A
18	1	HS1	Heat Sink, DER276-Diode, Alum 3003, 0.900" W x 0.860" H x 0.062" Thk		Custom
19	2	J1 J2	2 Position (1 x 2) header, 0.312 pitch, Vertical	26-50-3039	Molex
20	2	JP1 JP3	0 $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEY0R00V	Panasonic
21	1	JP2	Wire Jumper, Insulated, TFE, #22 AWG, 0.4 in	C2004-12-02	Alpha
22	1	L1	2.2 $\mu$ H, 6.0 A	RFB0807-2R2L	Coilcraft
23	1	NUT1	Nut, Hex, Metric, M3 SS	68024082	Import
24	2	R1 R2	4.7 M $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ475V	Panasonic
25	1	R3	3.9 M $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ395V	Panasonic
26	2	R4 R5	3 M $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ305V	Panasonic
27	1	R6	2 M $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ205V	Panasonic
28	2	R7 R8	39 $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ390V	Panasonic
29	1	R9	2.2 $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ2R2V	Panasonic
30	1	R10	191 k $\Omega$ , 1%, 1/4 W, Metal Film	MFR-25FBF-191K	Yageo
31	1	R11	15.4 k $\Omega$ , 1%, 1/4 W, Metal Film	MFR-25FBF-15K4	Yageo
32	1	R12	6.8 $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEYJ685V	Panasonic
33	1	R13	3.3 $\Omega$ , 5%, 1/8 W, Thick Film, 0805	ERJ-6GEYJ3R3V	Panasonic
34	1	R14	10 $\Omega$ , 5%, 1/4 W, Thick Film, 1206	ERJ-8GEYJ100V	Panasonic
35	1	R15	10 k $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEYJ103V	Panasonic
36	1	R16	2.2 k $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEYJ222V	Panasonic
37	1	R17	75 $\Omega$ , 5%, 1/10 W, Thick Film, 0603	ERJ-3GEYJ750V	Panasonic
38	1	R19	38.3 k $\Omega$ , 1%, 1/16 W, Thick Film, 0603	ERJ-3EKF3832V	Panasonic
39	1	R20	10 k $\Omega$ , 1%, 1/16 W, Thick Film, 0603	ERJ-3EKF1002V	Panasonic
40	1	RTV1	Thermally conductive Silicone Grease	120-SA	Wakefield
41	1	SCREW1	Screw, Phillips Flat Head, M3 x 6 mm, SS		Any RoHS Compliant Mfg.
42	1	T1	Bobbin, RM10, Vertical, 5 pins Assembled Transformer	P-1031 RLPI-1004	Pin Shine Renco Electronics
43	1	U1	TOP267KG, eSOP-12P	TOP267KG	Power Integrations
44	1	U2	Optocoupler, 35 V, CTR 300-600%, 4-DIP	PC817X4J000F	Sharp



45	1	U3	Shunt Regulator 2.5-30 V, 2%, SOT23-3	SC431CSK-2TRT	Semtech
46	1	VR1	200 V, 1.5 W, DO-41	BZY97C200-TR	Vishay
47	1	VR2	22 V, 500 mW, 5%, DO-35	BZX79-C22	Taiwan Semi
48	1	WASHER1	Washer, Lk, M 3 Zinc, Metric		



## 7 Transformer Specification

### 7.1 Electrical Diagram

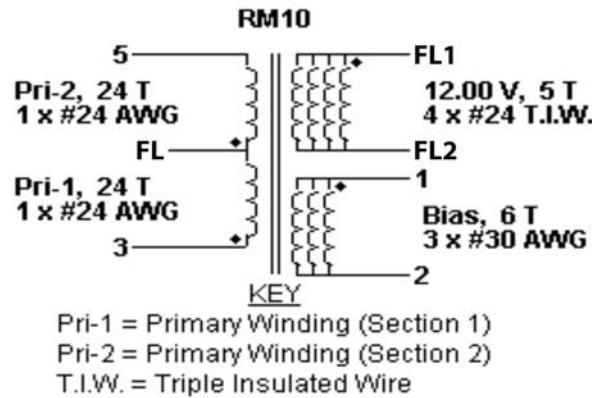


Figure 6 – Transformer Electrical Diagram.

### 7.2 Electrical Specifications

<b>Electrical Strength</b>	60 Hz 1 second, from pins 1, 2, 3, 4, 5 to pins FL1, FL2.	3000 VAC
<b>Primary Inductance</b>	Measured at 1 V pk-pk, typical switching frequency, between pin 3 to pin 5, with all other windings open.	1368 $\mu$ H $\pm$ 7%
<b>Primary Leakage Inductance</b>	Measured between pin 3 to pin 5, with all other windings shorted.	15 $\mu$ H

### 7.3 Materials

Item	Description
[1]	Core: RM10, 3F3 or Equivalent, gapped for ALG of 594 nH/t <sup>2</sup>
[2]	Bobbin: Generic, 5 primary + 0 secondary
[3]	Barrier Tape: Polyester film (1 mil base thickness), 9.60 mm wide
[4]	Separation Tape: Polyester film (1 mil base thickness), 9.60 mm wide
[5]	Varnish
[6]	Magnet Wire: #24 AWG, Solderable Double Coated
[7]	Triple Insulated Wire: #24 AWG
[8]	Magnet Wire: #30 AWG, Solderable Double Coated

### 7.4 Comments

1. Use of a grounded flux-band around the core may improve the EMI performance.
2. For non-margin wound transformers use triple insulated wire for all secondary windings.

### 7.5 Transformer Build Diagram

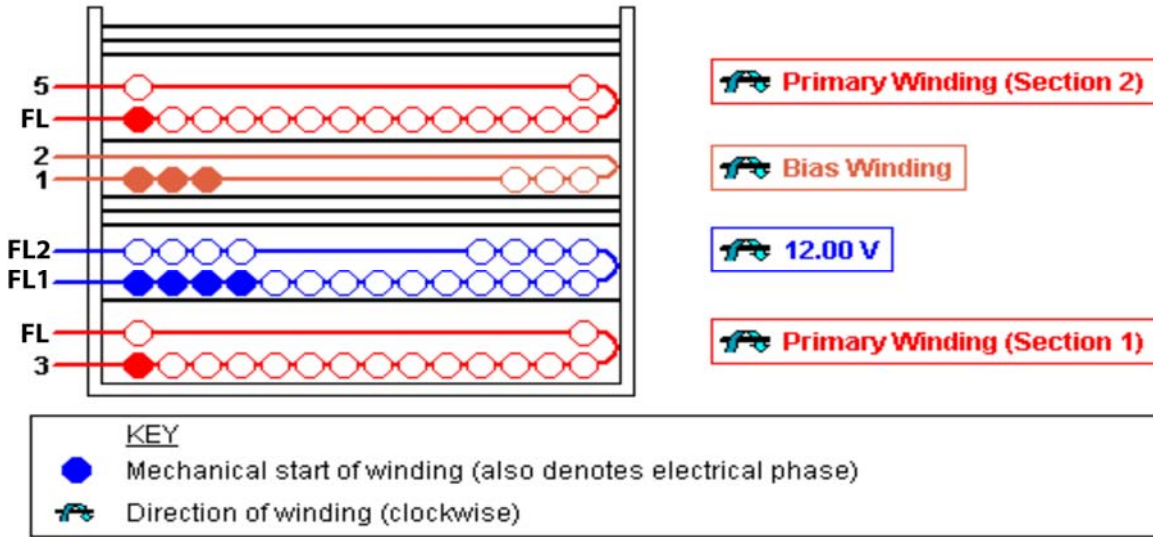


Figure 7 – Transformer Build Diagram.

### 7.6 Winding Instructions

<b>Primary Winding (Section 1)</b>	Start on pin(s) 3 and wind 24 turns (x 1 filar) of item [6] in 2 layer(s) from left to right. At the end of 1 <sup>st</sup> layer, continue to wind the next layer from right to left. On the final layer, spread the winding evenly across entire bobbin. Finish this winding on pin(s) FL. Add 1 layer of tape, item [3], for insulation.
<b>Secondary Winding</b>	Start on pin(s) FL1* and wind 5 turns (x 4 filar) of item [7]. Spread the winding evenly across entire bobbin. Wind in same rotational direction as primary winding. Finish this winding on pin(s) FL2*. Add 3 layers of tape, item [3], for insulation.
<b>Bias Winding</b>	Start on pin(s) 1 and wind 5 turns (x 3 filar) of item [8]. Wind in same rotational direction as primary winding. Spread the winding evenly across entire bobbin. Finish this winding on pin(s) 2. Add 3 layers of tape, item [3], for insulation.
<b>Primary Winding (Section 2)</b>	Start on pin(s) FL and wind 24 turns (x 1 filar) of item [6] in 2 layer(s) from left to right. At the end of 1 <sup>st</sup> layer, continue to wind the next layer from right to left. On the final layer, spread the winding evenly across entire bobbin. Finish this winding on pin(s) 5. Add 3 layers of tape, item [3], for insulation.
<b>Core Assembly</b>	Assemble and secure core halves. Item [1].
<b>Varnish</b>	Dip varnish uniformly in item [5]. Do not vacuum impregnate.

\*Flying Lead. Flying leads were required for this design to meet safety spacing requirements, the RM10 bobbin spacing from core to secondary pins is less than the required >6 mm.



## 8 Transformer Design Spreadsheet

ACDC_TOPSwitchJX_011911; Rev.1.4; Copyright Power Integrations 2010	INPUT	INFO	OUTPUT	UNIT	TOP_JX_011911: TOPSwitch-JX Continuous/Discontinuous Flyback Transformer Design Spreadsheet
<b>ENTER APPLICATION VARIABLES</b>					
VACMIN	85			Volts	Minimum AC Input Voltage
VACMAX	265			Volts	Maximum AC Input Voltage
fL	50			Hertz	AC Mains Frequency
VO	12.00			Volts	Output Voltage (main)
PO_AVG	40.00			Watts	Average Output Power
PO_PEAK			40.00	Watts	Peak Output Power
Heatsink Type	PCB		PCB		Heatsink Type
Enclosure	Open Frame				Open Frame enclosure assume sufficient airflow while adapter means a sealed enclosure.
n	0.89			%/100	Efficiency Estimate
Z	0.50				Loss allocation factor
VB	12			Volts	Bias Voltage - Verify that VB is > 8 V at no load and VMAX
tC	3.00			ms	Bridge Rectifier Conduction Time Estimate
CIN	220.0		220	uFarads	Input Filter Capacitor
<b>ENTER TOPSWITCH-JX VARIABLES</b>					
TOPSwitch-JX	TOP267K			Universal / Peak	115 Doubled/230V
<i>Chosen Device</i>		TOP267K	Power Out	45 W / 45 W	65W
KI	0.37				External Ilimit reduction factor (KI=1.0 for default ILIMIT, KI <1.0 for lower ILIMIT)
ILIMITMIN_EXT			1.036	Amps	Use 1% resistor in setting external ILIMIT
ILIMITMAX_EXT			1.191	Amps	Use 1% resistor in setting external ILIMIT
Frequency (F)=132kHz, (H)=66kHz	F		F		Select 'H' for Half frequency - 66kHz, or 'F' for Full frequency - 132kHz
fS			132000	Hertz	TOPSwitch-JX Switching Frequency: Choose between 132 kHz and 66 kHz
fSmin			119000	Hertz	TOPSwitch-JX Minimum Switching Frequency
fSmax			145000	Hertz	TOPSwitch-JX Maximum Switching Frequency
High Line Operating Mode			FF		Full Frequency, Jitter enabled
VOR	120.00			Volts	Reflected Output Voltage
VDS			10	Volts	TOPSwitch on-state Drain to Source Voltage
VD	0.50			Volts	Output Winding Diode Forward Voltage Drop
VDB	0.70			Volts	Bias Winding Diode Forward Voltage Drop
KP	0.40				Ripple to Peak Current Ratio (0.3 < KRP < 1.0 : 1.0 < KDP < 6.0)
<b>PROTECTION FEATURES</b>					
<b>LINE SENSING</b>					V pin functionality
VUV_STARTUP			94	Volts	Minimum DC Bus Voltage at which the power supply will start-up
VOV_SHUTDOWN			445	Volts	Typical DC Bus Voltage at which power supply will shut-down (Max)
RLS			4.0	M-ohms	Use two standard, 2 M-Ohm, 5%





					resistors in series for line sense functionality.
<b>OUTPUT OVERVOLTAGE</b>					
VZ			22	Volts	Zener Diode rated voltage for Output Overvoltage shutdown protection
RZ			5.1	k-ohms	Output OVP resistor. For latching shutdown use 20 ohm resistor instead
<b>OVERLOAD POWER LIMITING</b>					
Overload Current Ratio at VMAX			1.2		Enter the desired margin to current limit at VMAX. A value of 1.2 indicates that the current limit should be 20% higher than peak primary current at VMAX
Overload Current Ratio at VMIN			1.11		Margin to current limit at low line.
ILIMIT_EXT_VMIN			0.94	A	Peak primary Current at VMIN
ILIMIT_EXT_VMAX			0.68	A	Peak Primary Current at VMAX
RIL			15.49	k-ohms	Current limit/Power Limiting resistor.
RPL			N/A	M-ohms	Resistor not required. Use RIL resistor only
<b>ENTER TRANSFORMER CORE/CONSTRUCTION VARIABLES</b>					
<b>Core Type</b>	<b>RM10</b>		RM10		Core Type
Core		#N/A		P/N:	#N/A
Bobbin		#N/A		P/N:	#N/A
AE	0.8900		0.89	cm <sup>2</sup>	Core Effective Cross Sectional Area
LE	3.3900		3.39	cm	Core Effective Path Length
AL	5200.0		5200	nH/T <sup>2</sup>	Ungapped Core Effective Inductance
BW	9.6		9.6	mm	Bobbin Physical Winding Width
M	0.00			mm	Safety Margin Width (Half the Primary to Secondary Creepage Distance)
L	2.00				Number of Primary Layers
NS	5		5		Number of Secondary Turns
<b>DC INPUT VOLTAGE PARAMETERS</b>					
VMIN	110		110	Volts	Minimum DC Input Voltage
VMAX	400		400	Volts	Maximum DC Input Voltage
<b>CURRENT WAVEFORM SHAPE PARAMETERS</b>					
DMAX			0.55		Maximum Duty Cycle (calculated at PO_PEAK)
Iavg			0.41	Amps	Average Primary Current (calculated at average output power)
IP			0.94	Amps	Peak Primary Current (calculated at Peak output power)
IR			0.37	Amps	Primary Ripple Current (calculated at average output power)
IRMS			0.56	Amps	Primary RMS Current (calculated at average output power)
<b>TRANSFORMER PRIMARY DESIGN PARAMETERS</b>					
LP			1368	uHenries	Primary Inductance
LP Tolerance	7		7		Tolerance of Primary Inductance
NP			48		Primary Winding Number of Turns
NB			5		Bias Winding Number of Turns
ALG			594	nH/T <sup>2</sup>	Gapped Core Effective Inductance
BM			2998	Gauss	Maximum Flux Density at PO, VMIN (BM<3000)
BP			4082	Gauss	Peak Flux Density (BP<4200) at ILIMITMAX and LP_MAX. Note: Recommended values for adapters and external power supplies <=3600 Gauss
BAC			600	Gauss	AC Flux Density for Core Loss Curves (0.5 X Peak to Peak)
ur			1576		Relative Permeability of Ungapped

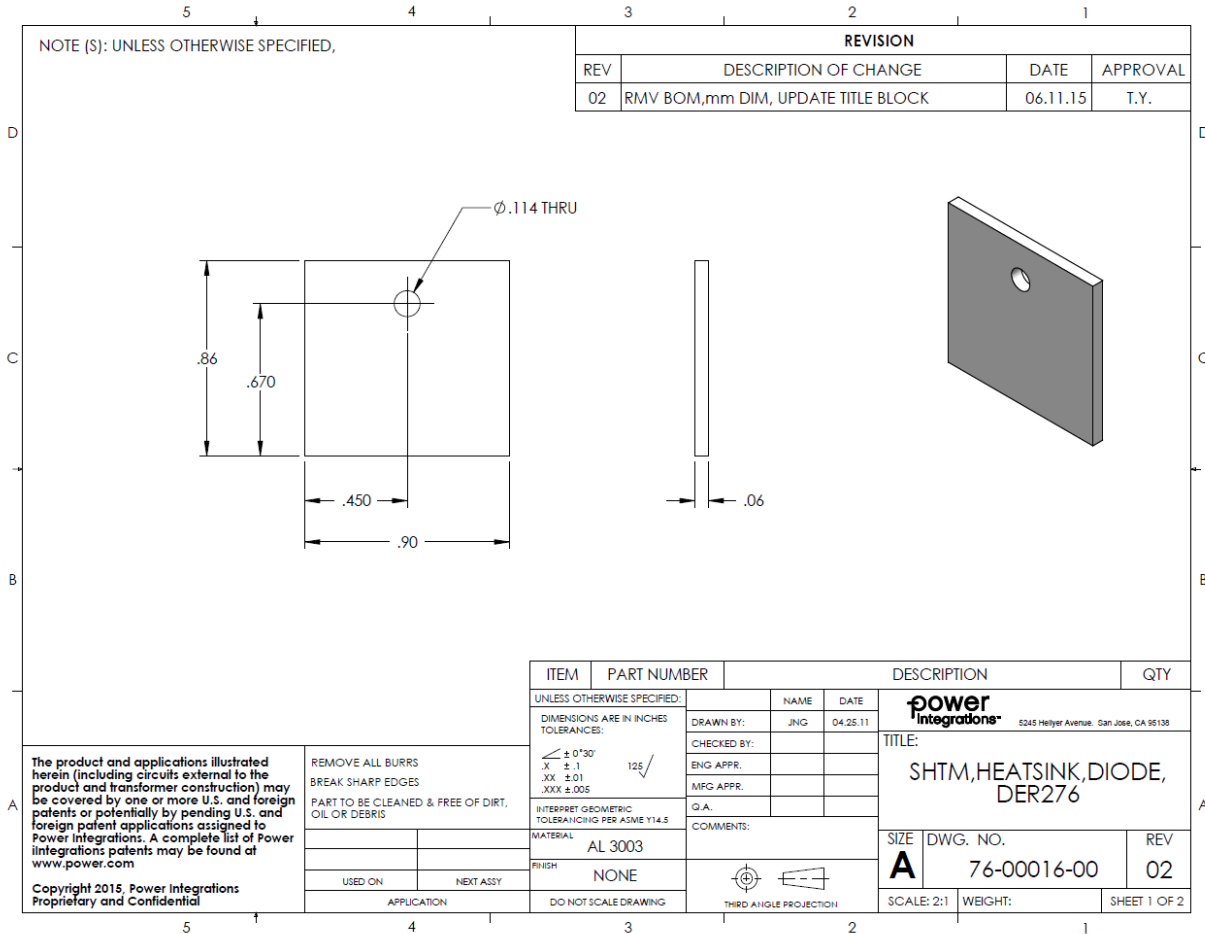
					Core
LG			0.17	mm	Gap Length (Lg > 0.1 mm)
BWE			19.2	mm	Effective Bobbin Width
OD			0.40	mm	Maximum Primary Wire Diameter including insulation
INS			0.06	mm	Estimated Total Insulation Thickness (= 2 * film thickness)
DIA			0.34	mm	Bare conductor diameter
AWG			28	AWG	Primary Wire Gauge (Rounded to next smaller standard AWG value)
CM			161	Cmils	Bare conductor effective area in circular mils
CMA			289	Cmils/Amp	Primary Winding Current Capacity (200 < CMA < 500)
Primary Current Density (J)			6.95	Amps/mm^2	Primary Winding Current density (3.8 < J < 9.75)
<b>TRANSFORMER SECONDARY DESIGN PARAMETERS (SINGLE OUTPUT EQUIVALENT)</b>					
<b>Lumped parameters</b>					
ISP			8.99	Amps	Peak Secondary Current
ISRMS			4.90	Amps	Secondary RMS Current
IO_PEAK			3.33	Amps	Secondary Peak Output Current
IO			3.33	Amps	Average Power Supply Output Current
IRIPPLE			3.59	Amps	Output Capacitor RMS Ripple Current
CMS			980	Cmils	Secondary Bare Conductor minimum circular mils
AWGS			20	AWG	Secondary Wire Gauge (Rounded up to next larger standard AWG value)
DIAS			0.81	mm	Secondary Minimum Bare Conductor Diameter
ODS			1.92	mm	Secondary Maximum Outside Diameter for Triple Insulated Wire
INSS			0.55	mm	Maximum Secondary Insulation Wall Thickness
<b>VOLTAGE STRESS PARAMETERS</b>					
VDRAIN			636	Volts	Maximum Drain Voltage Estimate (Includes Effect of Leakage Inductance)
PIVS			54	Volts	Output Rectifier Maximum Peak Inverse Voltage
PIVB			54	Volts	Bias Rectifier Maximum Peak Inverse Voltage
<b>TRANSFORMER SECONDARY DESIGN PARAMETERS (MULTIPLE OUTPUTS)</b>					
<b>1st output</b>					
VO1			12	Volts	Output Voltage
IO1_AVG			3.33	Amps	Average DC Output Current
PO1_AVG			40.00	Watts	Average Output Power
VD1			0.5	Volts	Output Diode Forward Voltage Drop
NS1			5.00		Output Winding Number of Turns
ISRMS1			4.898	Amps	Output Winding RMS Current
IRIPPLE1			3.59	Amps	Output Capacitor RMS Ripple Current
PIVS1			54	Volts	Output Rectifier Maximum Peak Inverse Voltage
CMS1			980	Cmils	Output Winding Bare Conductor minimum circular mils
AWGS1			20	AWG	Wire Gauge (Rounded up to next larger standard AWG value)
DIAS1			0.81	mm	Minimum Bare Conductor Diameter
ODS1			1.92	mm	Maximum Outside Diameter for Triple Insulated Wire
<b>2nd output</b>					
VO2				Volts	Output Voltage
IO2_AVG				Amps	Average DC Output Current



PO2_AVG			0.00	Watts	Average Output Power
VD2			0.7	Volts	Output Diode Forward Voltage Drop
NS2			0.28		Output Winding Number of Turns
ISRMS2			0.000	Amps	Output Winding RMS Current
IRIPPLE2			0.00	Amps	Output Capacitor RMS Ripple Current
PIVS2			2	Volts	Output Rectifier Maximum Peak Inverse Voltage
CMS2			0	Cmils	Output Winding Bare Conductor minimum circular mils
AWGS2			N/A	AWG	Wire Gauge (Rounded up to next larger standard AWG value)
DIAS2			N/A	mm	Minimum Bare Conductor Diameter
ODS2			N/A	mm	Maximum Outside Diameter for Triple Insulated Wire
<b>3rd output</b>					
VO3				Volts	Output Voltage
IO3_AVG				Amps	Average DC Output Current
PO3_AVG			0.00	Watts	Average Output Power
VD3			0.7	Volts	Output Diode Forward Voltage Drop
NS3			0.28		Output Winding Number of Turns
ISRMS3			0.000	Amps	Output Winding RMS Current
IRIPPLE3			0.00	Amps	Output Capacitor RMS Ripple Current
PIVS3			2	Volts	Output Rectifier Maximum Peak Inverse Voltage
CMS3			0	Cmils	Output Winding Bare Conductor minimum circular mils
AWGS3			N/A	AWG	Wire Gauge (Rounded up to next larger standard AWG value)
DIAS3			N/A	mm	Minimum Bare Conductor Diameter
ODS3			N/A	mm	Maximum Outside Diameter for Triple Insulated Wire
<b>Total Continuous Output Power</b>			40	Watts	Total Continuous Output Power
Negative Output			N/A		If negative output exists enter Output number; eg: If VO2 is negative output, enter 2

## 9 Diode Heat Sink

### 9.1 Diode Heat Sink Dimensions



### 9.2 Diode Heat Sink Assembly

NOTE(S): UNLESS OTHERWISE SPECIFIED,

REVISION			
REV	DESCRIPTION OF CHANGE	DATE	APPROVAL
02	CHG HARDWARE FROM M3 TO 4-40 (ITEMS4-6)	06.10.15	T.Y.

6	75-00001-00	SCR,4-40X1/4,PAN HD,PHILIPS,SS	1
5	75-00153-00	WASHER,LK,#4	1
4	75-00183-00	NUT,HEX,4-40, .18Wx.06T,STL ZNC	1
3	66-00084-00	THERMALLY CONDUCTIVE SILICONE GREASE	A/R
2	15-00887-00	100V,30A,SCHOTKY,TO-220AB	1
1	76-00016-01	SHTM,HEATSINK,DIODE,DER276	1

ITEM	PART NUMBER	DESCRIPTION	QTY
6	75-00001-00	SCR,4-40X1/4,PAN HD,PHILIPS,SS	1
5	75-00153-00	WASHER,LK,#4	1
4	75-00183-00	NUT,HEX,4-40, .18Wx.06T,STL ZNC	1
3	66-00084-00	THERMALLY CONDUCTIVE SILICONE GREASE	A/R
2	15-00887-00	100V,30A,SCHOTKY,TO-220AB	1
1	76-00016-01	SHTM,HEATSINK,DIODE,DER276	1

UNLESS OTHERWISE SPECIFIED:		NAME	DATE
DIMENSIONS ARE IN INCHES		JNG	04.25.11
TOLERANCES:		CHECKED BY:	
$\angle \pm 0^{\circ}30'$	125	ENG APPR:	
X $\pm .1$		MFG APPR:	
.XX $\pm .01$		Q.A.	
.XXX $\pm .005$		COMMENTS:	
INTERPRET GEOMETRIC TOLERANCING PER ASME Y14.5			
MATERIAL	SEE BOM		
FINISH	NONE		
USED ON	NEXT ASSY		
APPLICATION			
DO NOT SCALE DRAWING			

power Integrations™ E245 Hellyer Avenue, San Jose, CA 95138

TITLE:  
ASSY,HEATSINK,DIODE, DER276

SIZE DWG. NO. REV  
A 76-00016-00 02

SCALE: 2:1 WEIGHT: SHEET 2 OF 2

The product and applications illustrated herein (including circuits external to the product and transformer construction) may be covered by one or more U.S. and foreign patents or potentially by pending U.S. and foreign patent applications assigned to Power Integrations. A complete list of Power Integrations patents may be found at www.power.com

REMOVE ALL BURRS  
BREAK SHARP EDGES  
PART TO BE CLEANED & FREE OF DIRT, OIL OR DEBRIS

Copyright 2015, Power Integrations  
Proprietary and Confidential



### 10 Performance Data

All measurements performed at room temperature.

#### 10.1 Full load Efficiency

Efficiency data points were recorded after 30 minutes soak time at 25 °C ambient.

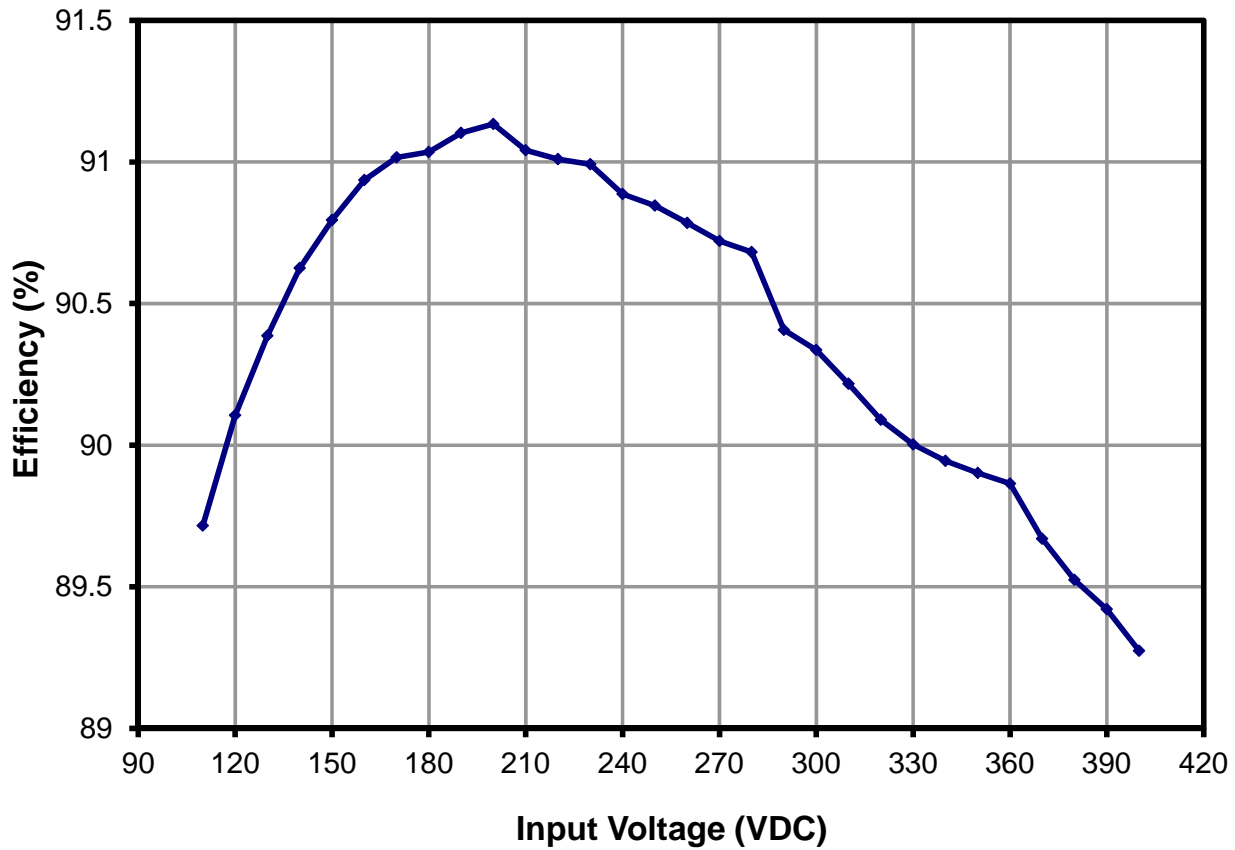


Figure 8 – Efficiency vs. Line Voltage, Full Load, Room Temperature.

$V_{IN}$ (V)	$I_{IN}$ (A)	$V_{OUT}$ (V)	$I_{OUT}$ (A)	Efficiency (%)
110	0.4052	12.001	3.333	89.74094
120	0.37	12	3.333	90.08108
130	0.3403	12.001	3.333	90.41645
140	0.3154	12.001	3.333	90.58641
150	0.2939	12.001	3.333	90.7323
160	0.2751	12.001	3.333	90.87453
170	0.2588	12.001	3.333	90.91584
180	0.2444	12.002	3.333	90.93168
190	0.2314	12.002	3.333	90.98546
200	0.2198	12.002	3.333	90.99788
210	0.2095	12.003	3.333	90.93306
220	0.2	12.003	3.333	90.92273
230	0.1914	12.004	3.333	90.88486
240	0.1836	12.004	3.333	90.79823
250	0.1764	12.004	3.333	90.72411
260	0.1698	12.004	3.333	90.62547
270	0.1636	12.004	3.333	90.57623
280	0.1581	12.005	3.333	90.38733
290	0.1528	12.006	3.333	90.3051
300	0.1478	12.006	3.333	90.24808
310	0.1432	12.005	3.333	90.13486
320	0.1389	12.005	3.333	90.02129
330	0.1349	12.006	3.333	89.88925
340	0.1311	12.006	3.333	89.7743
350	0.1275	12.007	3.333	89.67917
360	0.1241	12.007	3.333	89.5768
370	0.1208	12.006	3.333	89.52926
380	0.1178	12.007	3.333	89.4007
390	0.1151	12.008	3.333	89.15918
400	0.1123	12.008	3.333	89.09765

**Table 1** – Efficiency Data with Line Voltage Variation at Full Load.

### 10.2 Active Mode Efficiency

Data must be gathered at the following load points 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 15, 20, 25, 30, 40, 50, 60, 70, 75, 80, 90 and 100 % load with 380 VDC input voltage

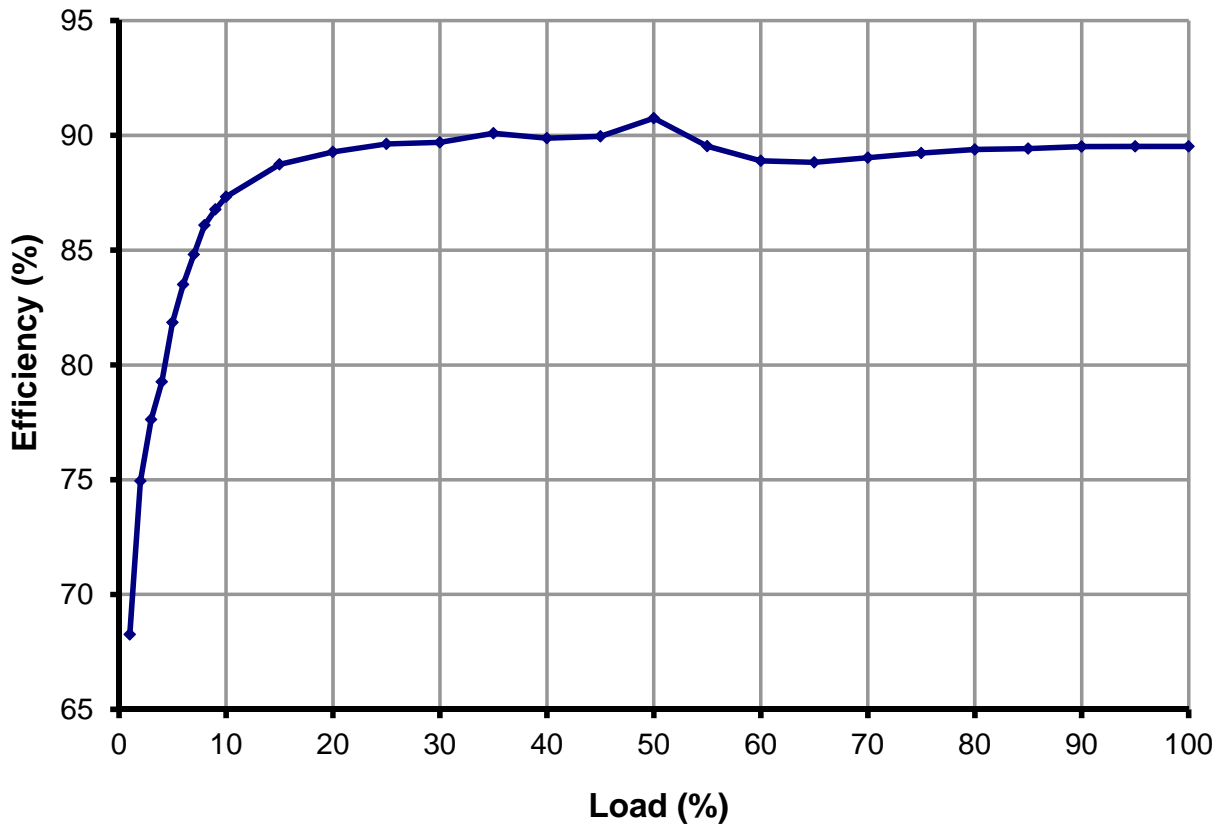


Figure 9 – Efficiency vs. Load Current (1-100%), Room Temperature.



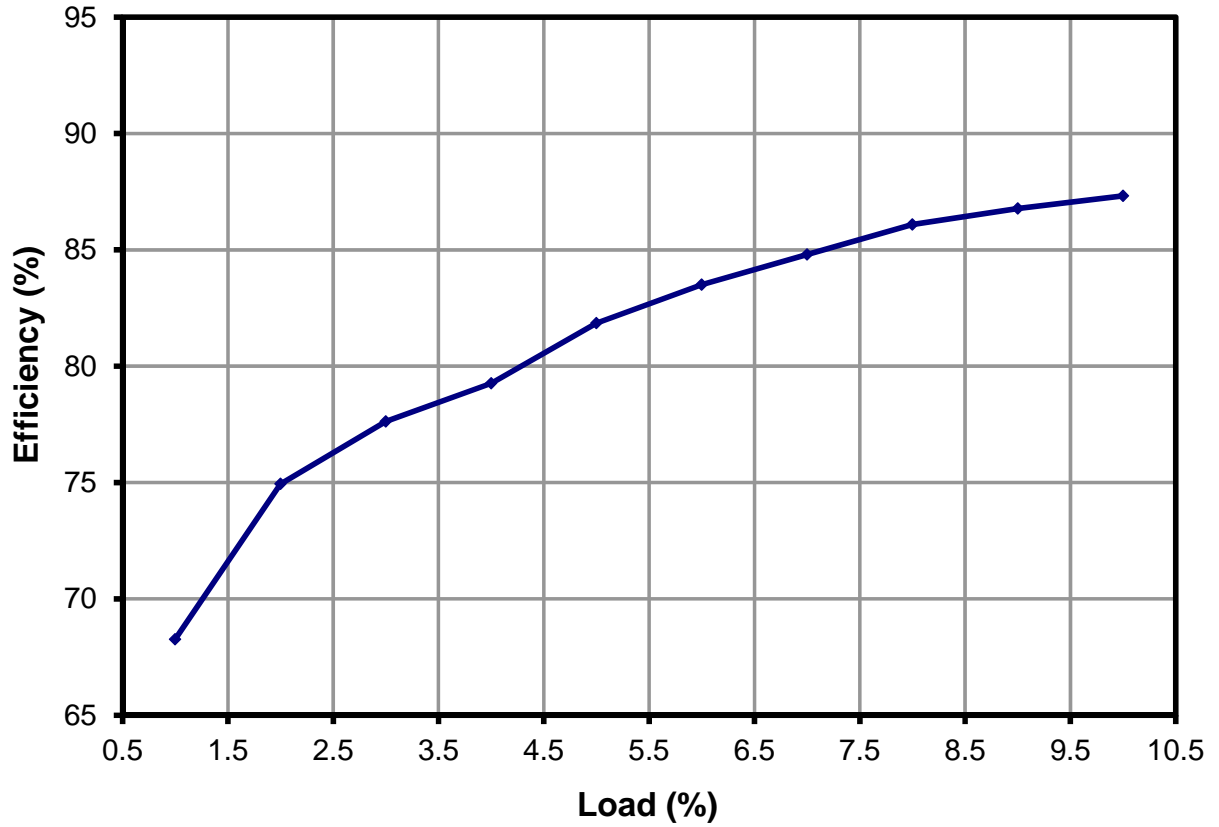


Figure 10 – Efficiency vs. Load Current (1-10%), Room Temperature.



$V_{IN}$ (V)	$I_{IN}$ (A)	$V_{OUT}$ (V)	$I_{OUT}$ (A)	Efficiency (%)	Load (%)
380	0.1178	12.007	3.334	89.42753	100
380	0.1119	12.007	3.1673	89.43552	95
380	0.10608	12.008	3.0006	89.38439	90
380	0.1003	12.008	2.8339	89.28339	85
380	0.0945	12.009	2.6672	89.19634	80
380	0.08876	12.009	2.5005	89.02927	75
380	0.08297	12.009	2.3338	88.89264	70
380	0.07727	12.01	2.1671	88.63953	65
380	0.07147	12.01	2.0004	88.46113	60
380	0.06524	12.011	1.8337	88.84028	55
380	0.05834	12.01	1.667	90.30849	50
380	0.053	12.01	1.5003	89.46675	45
380	0.04677	12.01	1.3336	90.11926	40
380	0.04108	12.01	1.1669	89.77649	35
380	0.03528	12.011	1.0002	89.60946	30
380	0.02956	12.01	0.8335	89.11701	25
380	0.0237	12.009	0.6668	88.91407	20
380	0.017895	12.009	0.5001	88.31783	15
380	0.012115	12.009	0.3334	86.96919	10
380	0.011007	12.008	0.30006	86.14424	9
380	0.00986	12.008	0.26672	85.48024	8
380	0.008753	12.008	0.23338	84.25463	7
380	0.007624	12.008	0.20004	82.9127	6
380	0.006491	12.008	0.1667	81.15421	5
380	0.005339	12.007	0.13336	78.92536	4
380	0.004079	12.007	0.10002	77.47901	3
380	0.002812	12.007	0.06668	74.92577	2
380	0.001543	12.007	0.03334	68.27325	1

**Table 2** – Efficiency Data with Load Variation at 380 VDC Input.

### 10.3 No-load Input Power

DC Input supply without EMI filter.

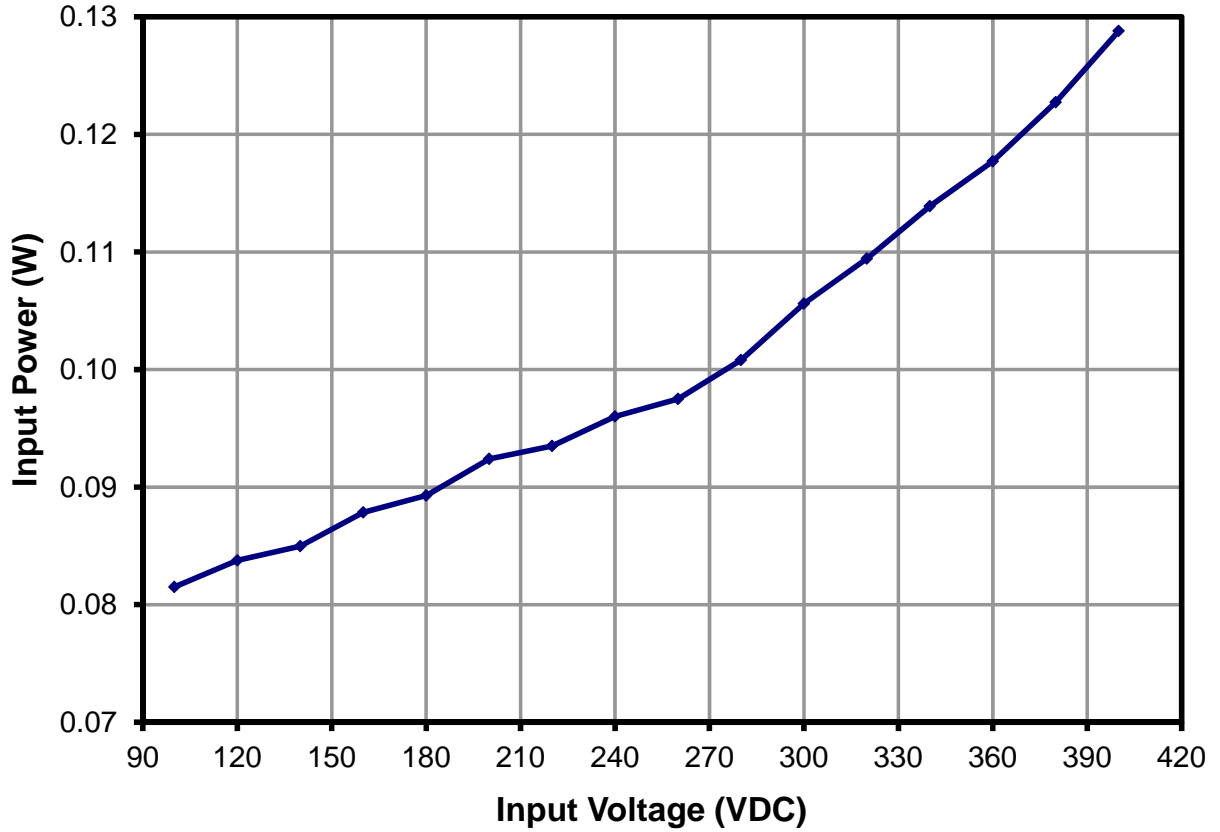


Figure 11 – Zero Load Input Power vs. Input Line Voltage, Room Temperature.



$V_{IN}$ (VDC)	$I_{IN}$ (A)	$P_{IN}$ (W)
100	0.000826	0.0826
120	0.000698	0.08376
140	0.000612	0.08568
160	0.000545	0.0872
180	0.000504	0.09072
200	0.000456	0.0912
220	0.000418	0.09196
240	0.000388	0.09312
260	0.000374	0.09724
280	0.000361	0.10108
300	0.000349	0.1047
320	0.000341	0.10912
340	0.000335	0.1139
360	0.000331	0.11916
380	0.000325	0.1235
400	0.000323	0.1292

**Table 3** – No-Load Power.

### 10.4 Regulation

#### 10.4.1 Load Regulation

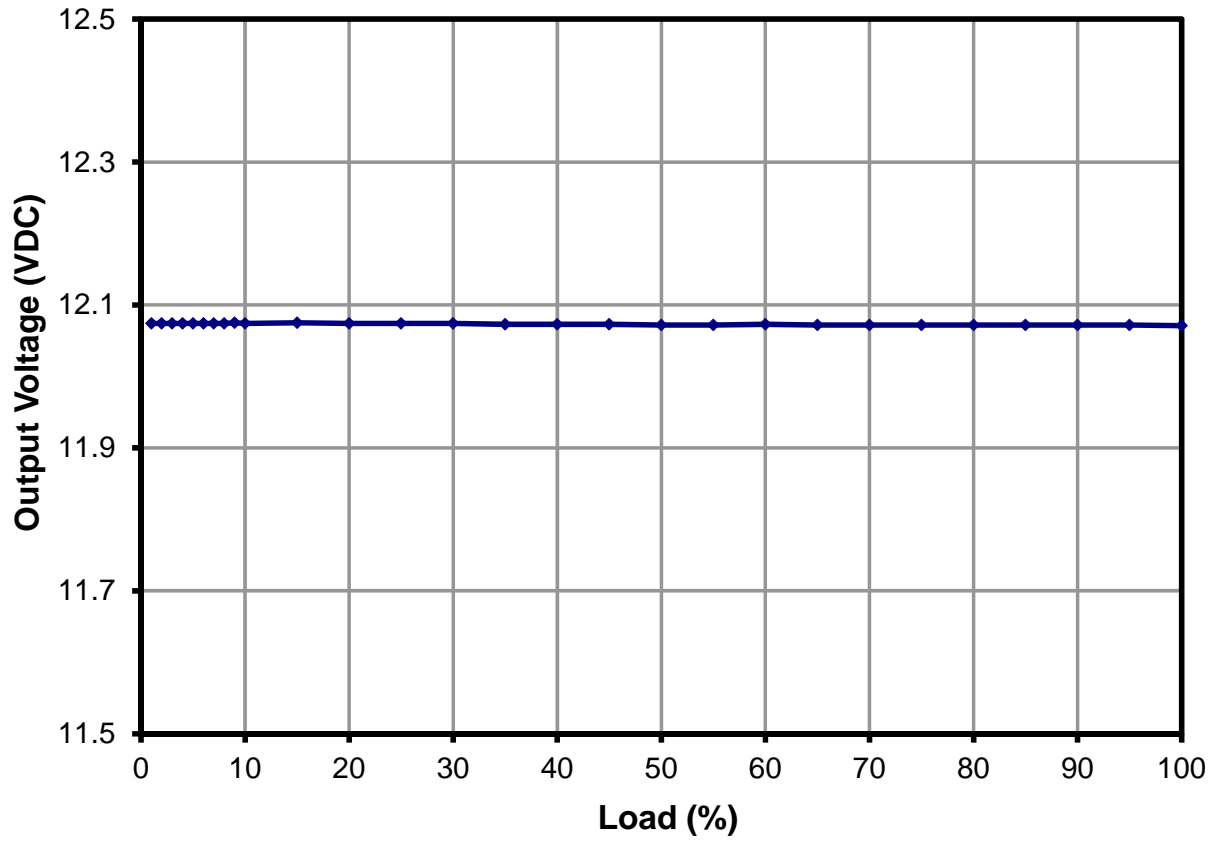
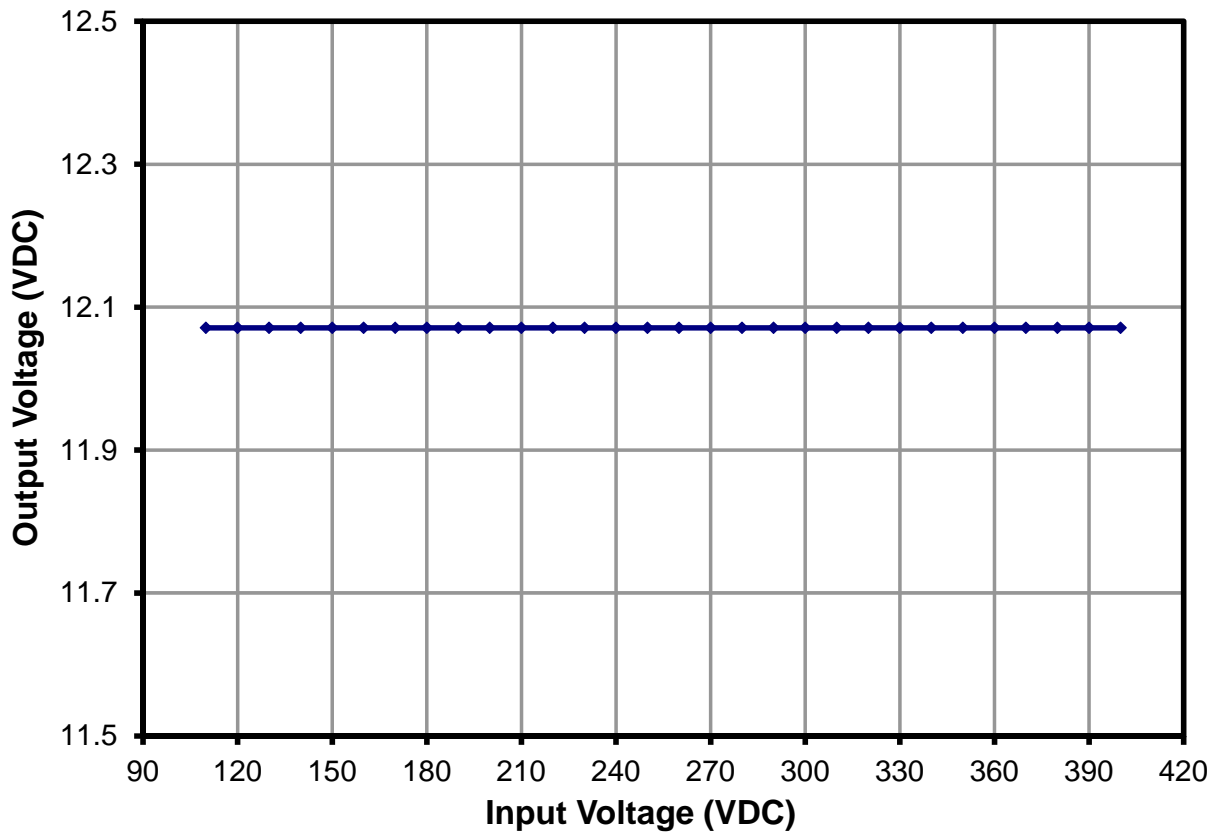


Figure 12 – Load Regulation, Room Temperature, 380 VDC.



**10.5 Line Regulation**



**Figure 13** – Line Regulation, Room Temperature, Full Load.



## 11 Thermal Performance

### 11.1 Thermal Test Results at Room Temperature

Test result after 2 hours running continuously at full load at 110 VDC open frame on bench at room temperature.

Item	Temperature (°C)
	110 VDC
Ambient	25
Transformer (T1)	55.6
TOP267KG (U1)	72.4
Snubber Diode (D1)	54.9
Snubber TVS (VR1)	49.9
Output Diode (D4)	80.7
Output Capacitor (C9)	57

**Table 4** – Room Temperature Data.

### 11.2 Thermal Scan at Room Temperature

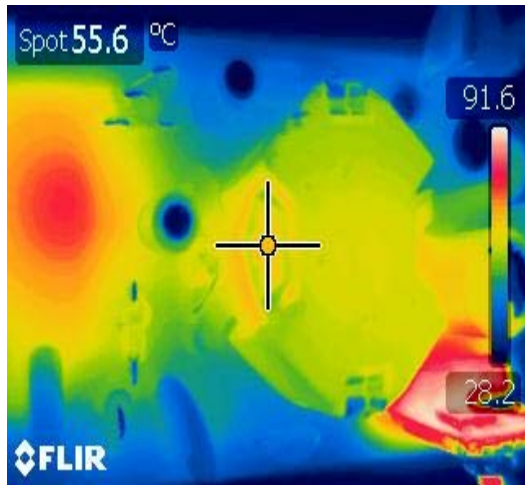


Figure 14 – Transformer (T1) Thermal Scan.



Figure 15 – TOP267KG (U1) Thermal Scan.

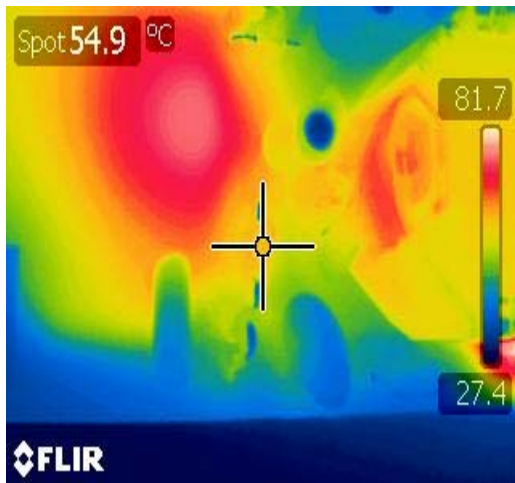


Figure 16 – Snubber Diode (D1) Thermal Scan.

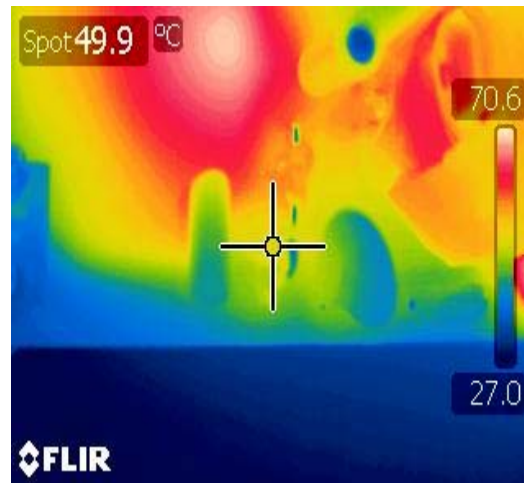


Figure 17 – Snubber TVS (VR1) Thermal Scan.

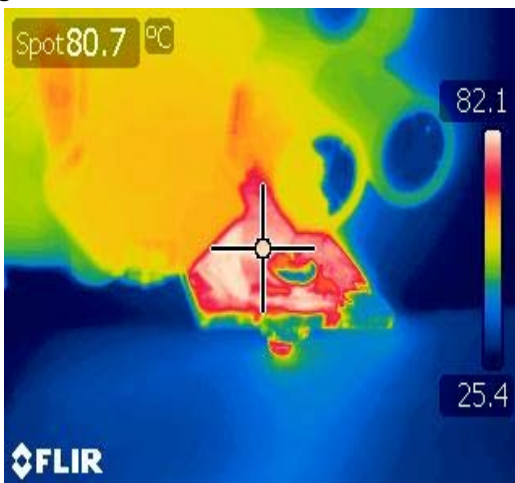


Figure 18 – Output Diode (D4) Thermal Scan.

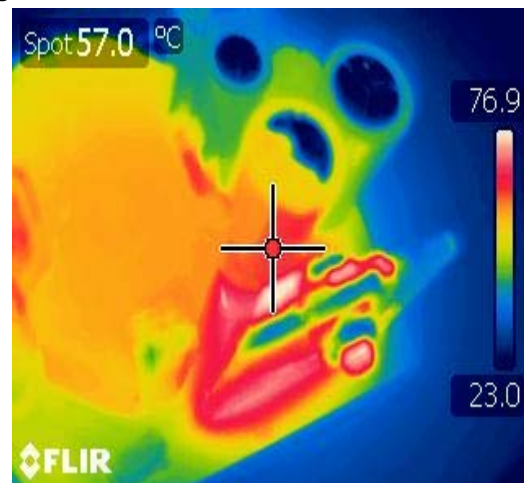


Figure 19 – Output Capacitor (C9) Thermal Scan.



### 11.3 Thermal Chamber Test Data

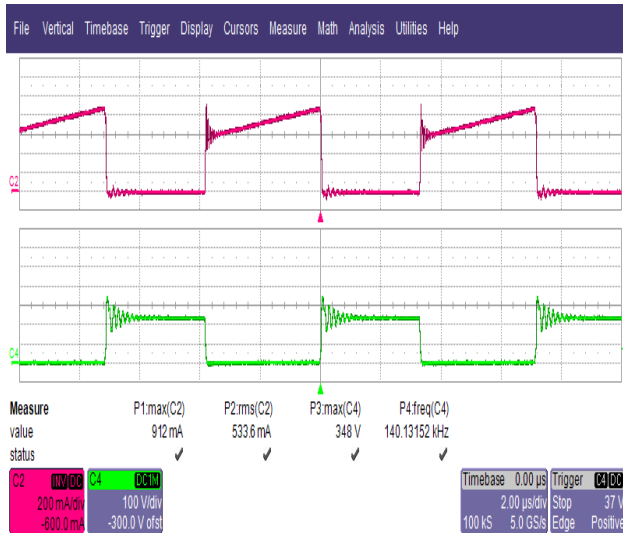
Test result after 2 hours running continuously at full load by using thermal chamber. All measurements made using thermocouples attached to individual components on the circuit board

Item	Temperature (°C)	
	110 VDC	400 VDC
Ambient	41	41.5
Transformer (T1)	72.9	73.2
TOP267KG (U1)	90.9	102.6
Snubber Diode (D1)	74	76.2
Snubber TVS (VR1)	67.6	69
Output Diode (D4)	95.9	96.5
Output Capacitor (C9)	71	68

**Table 5** – Thermal Chamber Temperature Data at 40 °C.

## 12 Waveforms

### 12.1 Drain Voltage and Current, Normal Operation



**Figure 20 – 110 VDC, Full Load.**  
 Upper:  $I_{DRAIN}$ , 0.2 A / div.  
 Lower:  $V_{DRAIN}$ , 100 V, 2  $\mu$ s / div.



**Figure 21 – 400 VDC, Full Load.**  
 Upper:  $I_{DRAIN}$ , 0.2 A / div.  
 Lower:  $V_{DRAIN}$ , 100 V, 2  $\mu$ s / div.

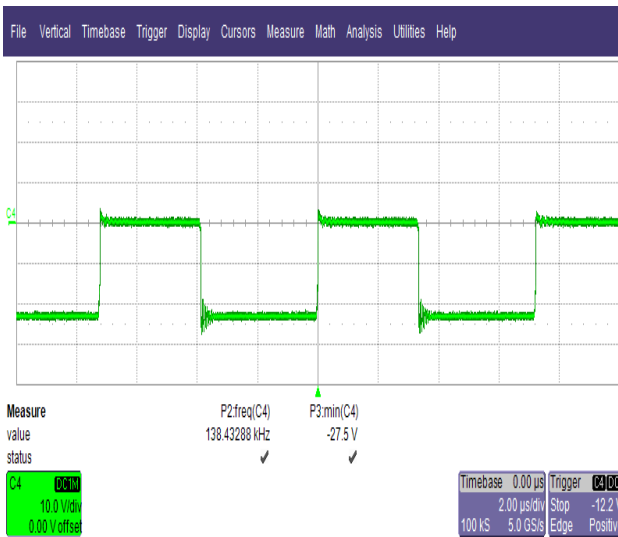


**Figure 22 – 110 VDC, Over Load (125%).**  
 Upper:  $I_{DRAIN}$ , 0.2 A / div.  
 Lower:  $V_{DRAIN}$ , 100 V, 2  $\mu$ s / div.

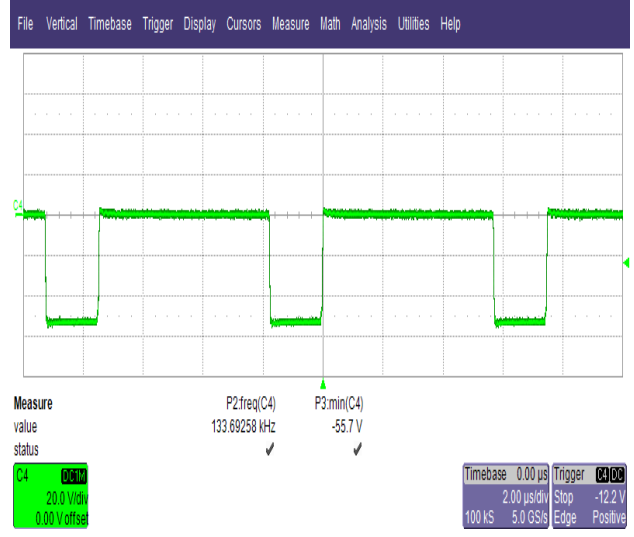


**Figure 23 – 400 VDC, Over Load (125%).**  
 Upper:  $I_{DRAIN}$ , 0.2 A / div.  
 Lower:  $V_{DRAIN}$ , 100 V, 2  $\mu$ s / div.

### 12.2 Rectifier Peak Inverse Voltage (PIV)



**Figure 24** – 110 VDC 100% Load.  
10 V / div., 2 μs / div.

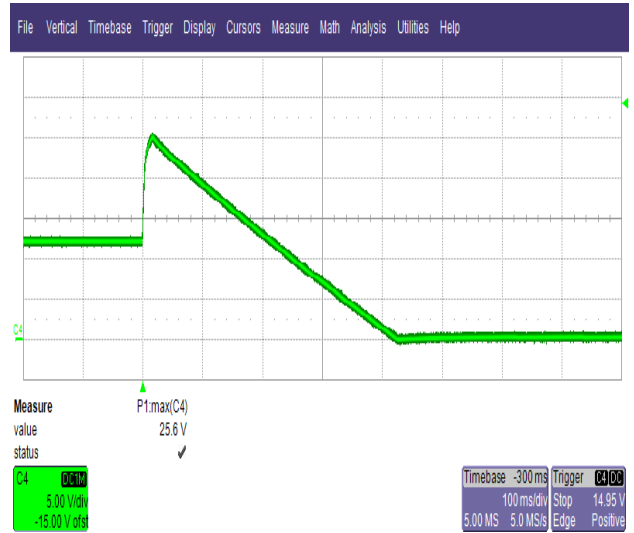


**Figure 25** – 400 VDC 100% Load.  
10 V / div., 2 μs / div.

### 12.3 Output OVP Profile



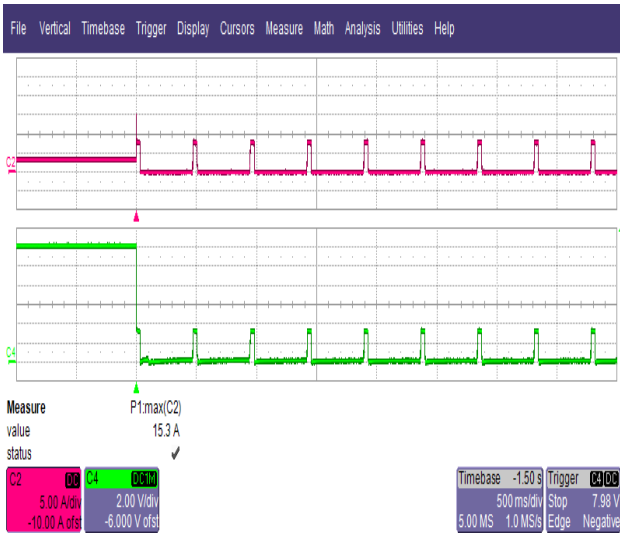
**Figure 26** – OVP Profile, 110 VDC, 100 mA Load.  
5 V / div. & 100 ms / div.



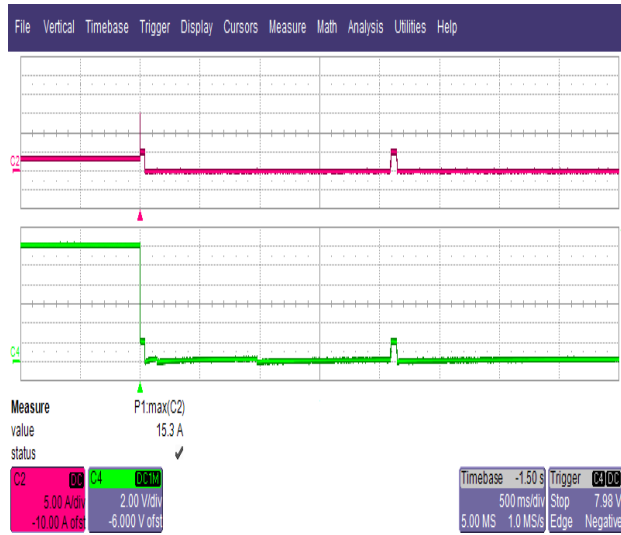
**Figure 27** – OVP Profile, 380 VDC, 100 mA Load.  
5 V / div. & 100 ms / div.



### 12.4 OCP Profile



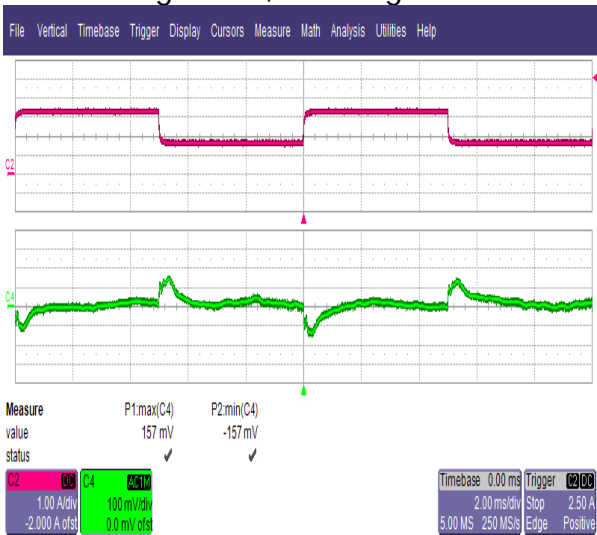
**Figure 28** – OCP Profile, 110 VDC.  
 Upper:  $I_{OUT}$ , 5 A / div.  
 Lower:  $V_{OUT}$ , 2 V, 500 ms / div.



**Figure 29** – OCP Profile, 400 VDC.  
 Upper:  $I_{OUT}$ , 5 A / div.  
 Lower:  $V_{OUT}$ , 2 V, 500 ms / div.

### 12.5 Load Transient Response (50% to 100% Load Step)

In the figures shown below, signal averaging was used to better enable viewing the load transient response. The oscilloscope was triggered using the load current step as a trigger source. Since the output switching and line frequency occur essentially at random with respect to the load transient, contributions to the output ripple from these sources will average out, leaving the contribution only from the load step response.



**Figure 30** – Transient Response, 110 VDC.  
 50-100-50% Load Step.  
 Upper:  $I_{LOAD}$ , 1 A / div.  
 Lower:  $V_{OUT}$ , 0.1 V / div., 2 ms / div.



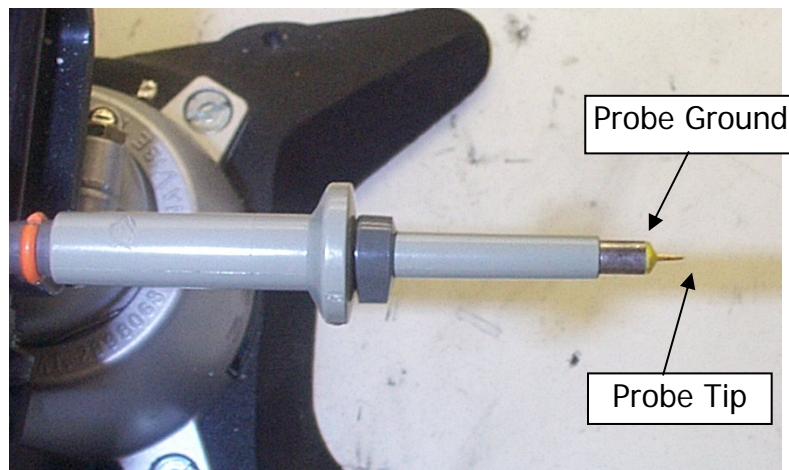
**Figure 31** – Transient Response, 380 VDC.  
 50-100-50% Load Step.  
 Upper:  $I_{LOAD}$ , 1 A / div.  
 Lower:  $V_{OUT}$ , 0.1 V / div., 2 ms / div.

## 12.6 Output Ripple Measurements

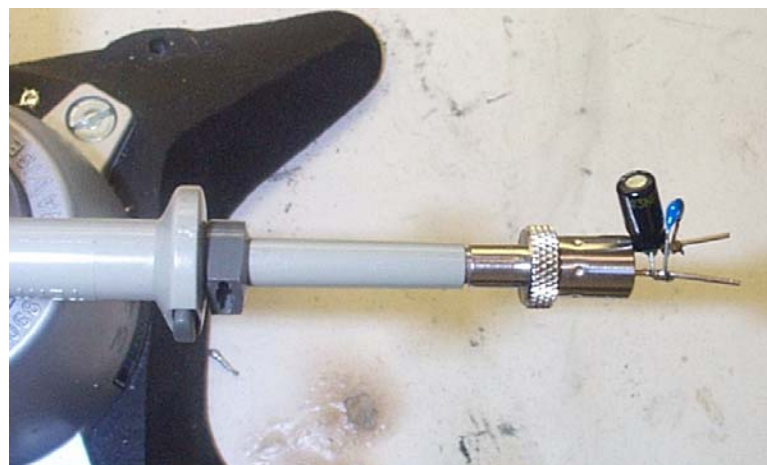
### 12.6.1 Ripple Measurement Technique

For DC output ripple measurements, a modified oscilloscope test probe must be utilized in order to reduce spurious signals due to pickup. Details of the probe modification are provided in the Figures below.

The 4987BA probe adapter is affixed with two capacitors tied in parallel across the probe tip. The capacitors include one (1) 0.1  $\mu\text{F}/50\text{ V}$  ceramic type and one (1) 1.0  $\mu\text{F}/50\text{ V}$  aluminum electrolytic. The aluminum electrolytic type capacitor is polarized, so proper polarity across DC outputs must be maintained (see below).

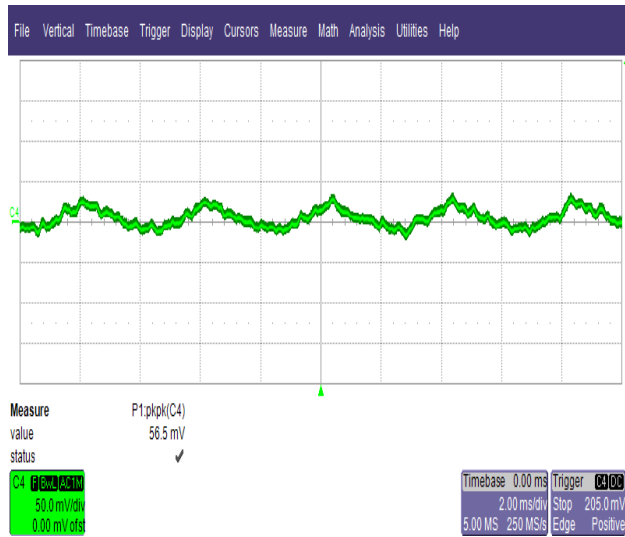


**Figure 32** – Oscilloscope Probe Prepared for Ripple Measurement. (End Cap and Ground Lead Removed)

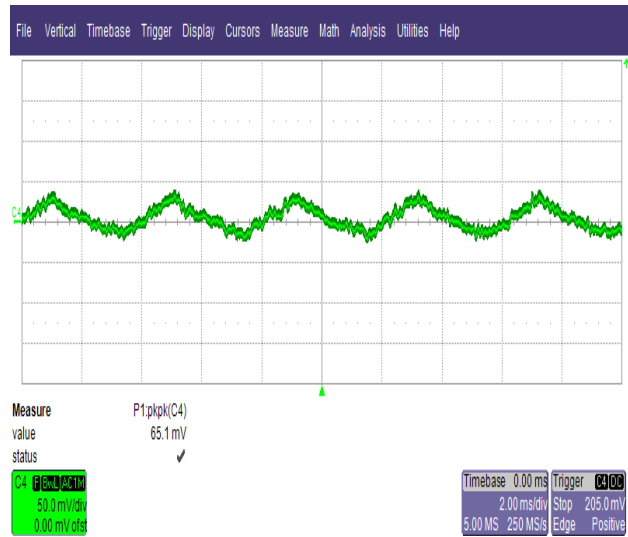


**Figure 33** – Oscilloscope Probe with Probe Master ([www.probemaster.com](http://www.probemaster.com)) 4987A BNC Adapter. (Modified with wires for ripple measurement, and two parallel decoupling capacitors added)

### 12.6.2 Measurement Results



**Figure 34** – Output Voltage Ripple, 110 VDC, Full Load. 2 ms, 50 mV / div.



**Figure 35** – Output Voltage Ripple, 380 VDC, Full Load. 2 ms, 50 mV / div.

### 13 Control Loop Measurements

EQUIPMENT: Frequency Response Analyzer  
 Model 5060A  
 VENABLE

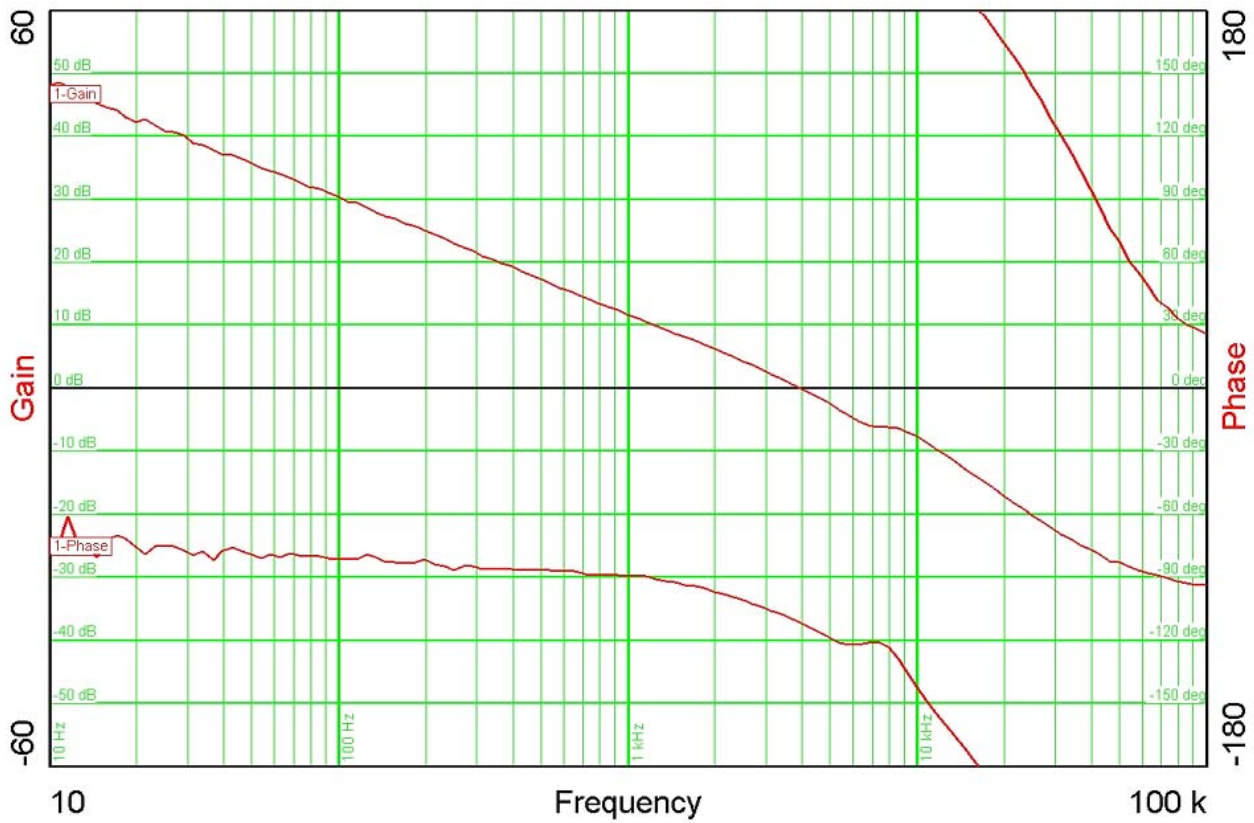
#### 13.1 110 VDC Maximum Load



**Figure 36** – Gain-Phase Plot, Maximum Steady-State Load.  
 Vertical Scale: Gain = 10 dB / div., Phase = 30 ° / div.  
 110 VDC – Crossover Frequency = 1.8 kHz Phase Margin = 50°.



### 13.2 380 VDC Maximum Load



**Figure 37** – Gain-Phase Plot, Maximum Steady-State Load.  
Vertical Scale: Gain = 10 dB / div., Phase = 30 ° / div.  
380 VDC - Crossover Frequency = 3.9 kHz Phase Margin = 70°.



**14 Revision History**

<b>Date</b>	<b>Author</b>	<b>Revision</b>	<b>Description &amp; changes</b>	<b>Reviewed</b>
13-May-11	SS	1.0	Initial Release	Apps & Mktg
17-May-12	KM	1.1	Added Renco as a Transformer Supplier	
03-Aug-15	KM	1.2	Updated Heat Sink Drawing and Brand Style	



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